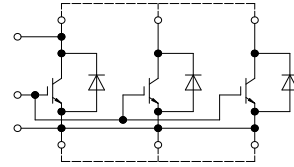


IHM-B Modul mit schnellem Trench/Feldstopp IGBT4 und Emitter Controlled Diode und bereits aufgetragenem Thermal Interface Material

IHM-B module with fast Trench/Fieldstop IGBT4 and Emitter Controlled diode and pre-applied Thermal Interface Material



external connection
(to be done)

$V_{CES} = 1700V$

$I_{C\ nom} = 3600A / I_{CRM} = 7200A$

Typische Anwendungen

- Hochleistungsumrichter
- Motorantriebe

Elektrische Eigenschaften

- Erweiterte Sperrschichttemperatur $T_{vj\ op}$
- Niedrige Schaltverluste
- Niedriges V_{CEsat}
- $T_{vj\ op} = 150^{\circ}C$

Mechanische Eigenschaften

- 4 kV AC 1min Isolationsfestigkeit
- Gehäuse mit CTI > 400
- Große Luft- und Kriechstrecken
- Hohe Leistungsdichte
- IHM B Gehäuse
- Kupferbodenplatte
- RoHS konform
- Thermisches Interface Material bereits aufgetragen

Typical Applications

- High power converters
- Motor drives

Electrical Features

- Extended operating temperature $T_{vj\ op}$
- Low switching losses
- Low V_{CEsat}
- $T_{vj\ op} = 150^{\circ}C$

Mechanical Features

- 4 kV AC 1min insulation
- Package with CTI > 400
- High creepage and clearance distances
- High power density
- IHM B housing
- Copper base plate
- RoHS compliant
- Pre-applied Thermal Interface Material

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

IGBT, Wechselrichter / IGBT, Inverter Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1700	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 70^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$	3600	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	7200	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 3600\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,95	2,30	V	
	$I_C = 3600\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$		2,35	2,75	V	
	$I_C = 3600\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		2,45	2,90	V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 145\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		V_{GEth}	5,20	5,80	6,40	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		Q_G		38,0		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		R_{Gint}		0,54		Ω
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}		295		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}		9,50		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1700\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}			5,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}			400	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 3600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 0,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$	t_{don}	0,66		μs	
		$T_{vj} = 125^{\circ}\text{C}$		0,74		μs	
		$T_{vj} = 150^{\circ}\text{C}$		0,78		μs	
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 3600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 0,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$	t_r	0,28		μs	
		$T_{vj} = 125^{\circ}\text{C}$		0,29		μs	
		$T_{vj} = 150^{\circ}\text{C}$		0,295		μs	
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 3600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 0,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$	t_{doff}	1,60		μs	
		$T_{vj} = 125^{\circ}\text{C}$		1,80		μs	
		$T_{vj} = 150^{\circ}\text{C}$		1,85		μs	
Fallzeit, induktive Last Fall time, inductive load	$I_C = 3600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 0,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$	t_f	0,175		μs	
		$T_{vj} = 125^{\circ}\text{C}$		0,315		μs	
		$T_{vj} = 150^{\circ}\text{C}$		0,395		μs	
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 3600\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 12000\text{ A}/\mu\text{s}$ ($T_{vj} = 150^{\circ}\text{C}$) $R_{Gon} = 0,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$	E_{on}	650		mJ	
		$T_{vj} = 125^{\circ}\text{C}$		800		mJ	
		$T_{vj} = 150^{\circ}\text{C}$		900		mJ	
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 3600\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 2300\text{ V}/\mu\text{s}$ ($T_{vj} = 150^{\circ}\text{C}$) $R_{Goff} = 0,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$	E_{off}	1100		mJ	
		$T_{vj} = 125^{\circ}\text{C}$		1500		mJ	
		$T_{vj} = 150^{\circ}\text{C}$		1600		mJ	
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 1000\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		I_{SC}		14000	A	
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT valid with IFX pre-applied thermal interface material		R_{thJH}		9,85	K/kW	
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{op}}$	-40	150	$^{\circ}\text{C}$	

Diode, Wechselrichter / Diode, Inverter

Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1700	V
Dauergleichstrom Continuous DC forward current		I_F	3600	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	7200	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	1800 1700	kA^2s kA^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.		
Durchlassspannung Forward voltage	$I_F = 3600\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 3600\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 3600\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F		1,80 1,90 1,95	2,20 2,30 2,40	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 3600\text{ A}, -di_F/dt = 12000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}		2600 3150 3300		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 3600\text{ A}, -di_F/dt = 12000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r		730 1350 1550		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 3600\text{ A}, -di_F/dt = 12000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}		490 950 1100		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode valid with IFX pre-applied thermal interface material		R_{thJH}			16,4	K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

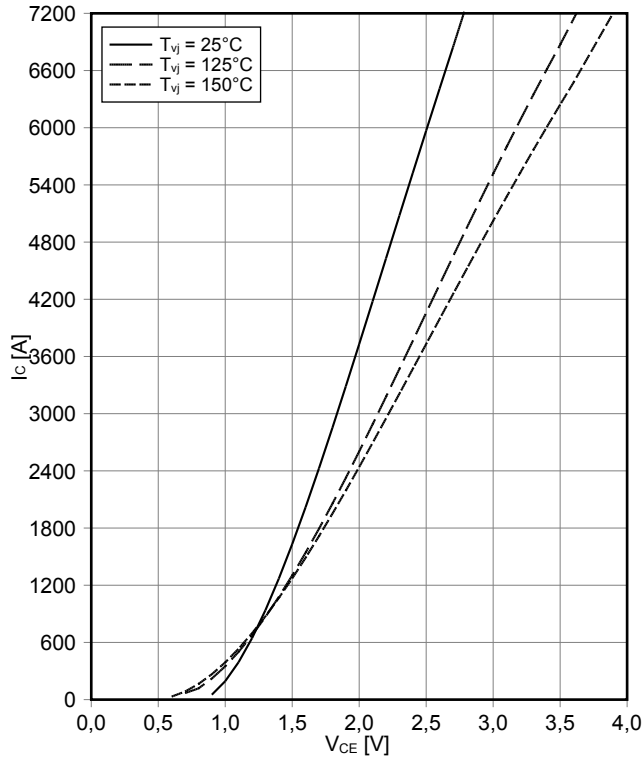
Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	4,0		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		32,2 32,2		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		19,1 19,1		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 400		
			min.	typ.	max.
Modulstreuinduktivität Stray inductance module		L _{sCE}		6,0	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T _H = 25°C, pro Schalter / per switch	R _{CC'+EE'}		0,085	mΩ
Lagertemperatur Storage temperature		T _{stg}	-40		125 °C
Höchstzulässige Bodenplattenbetriebstemperatur Maximum baseplate operation temperature		T _{BPmax}			125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	4,25		5,75 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M4 - Montage gem. gültiger Applikationsschrift Schraube M8 - Montage gem. gültiger Applikationsschrift Screw M4 - Mounting according to valid application note Screw M8 - Mounting according to valid application note	M	1,8 8,0	- -	2,1 10 Nm
Gewicht Weight		G		1900	g

Lagerung und Transport von Modulen mit TIM laut AN2012-07
Storage and shipment of modules with TIM according to AN2012-07

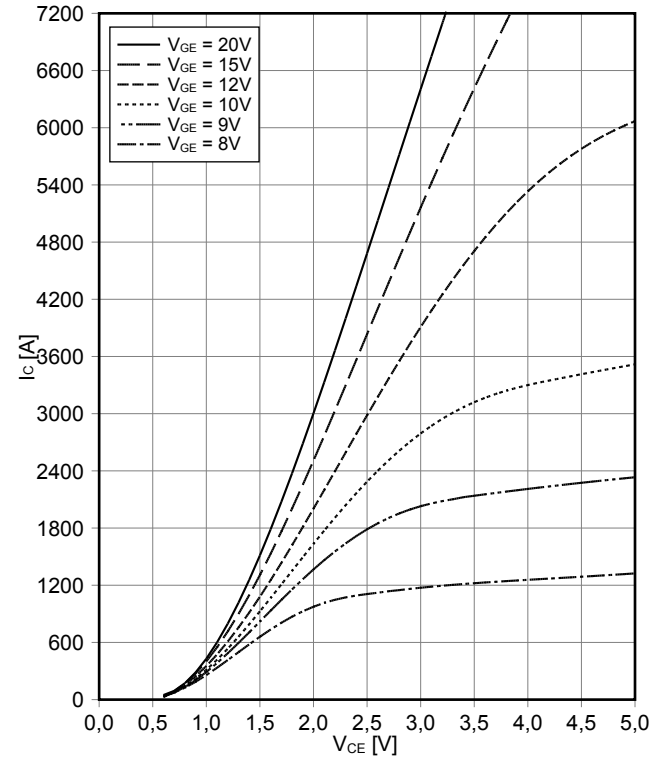
Ausgangskennlinie IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



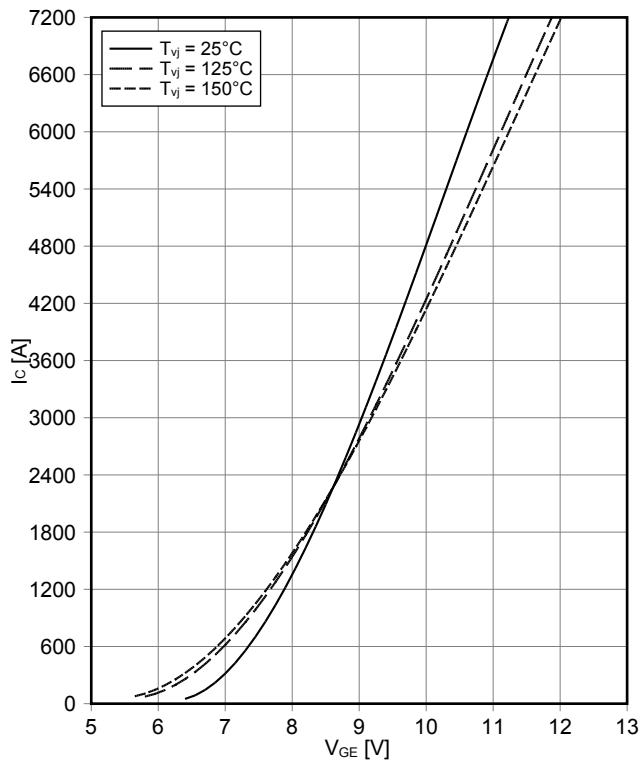
Ausgangskennlinienfeld IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



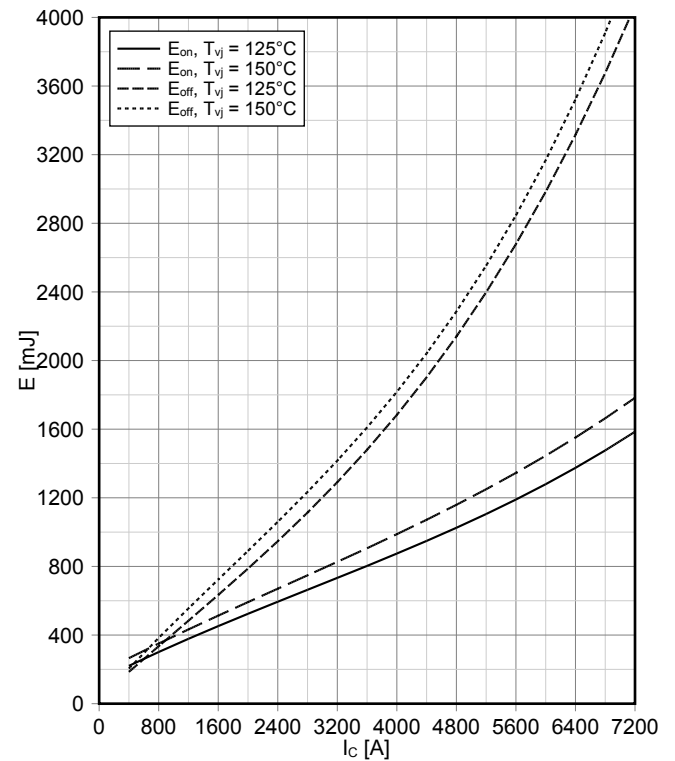
Übertragungscharakteristik IGBT, Wechselrichter (typisch)
transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



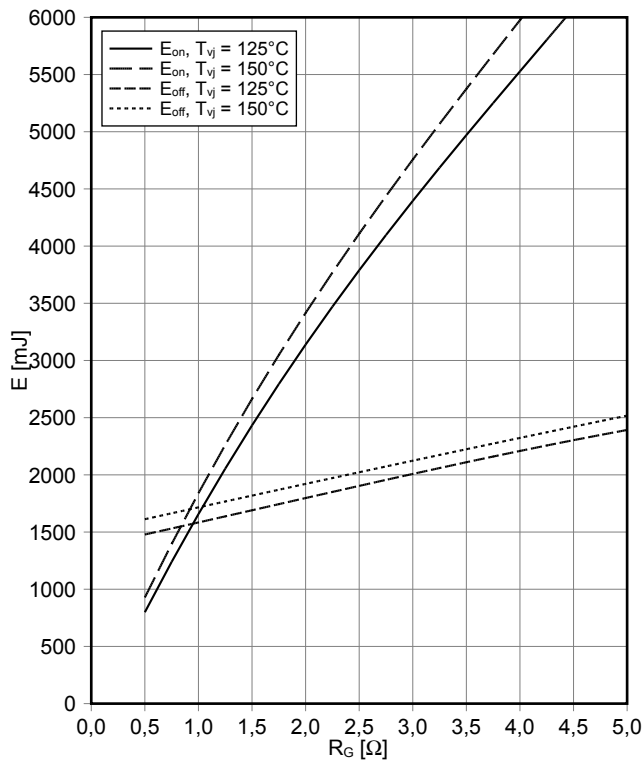
Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 0.5\ \Omega$, $R_{Goff} = 0.5\ \Omega$, $V_{CE} = 900\text{ V}$



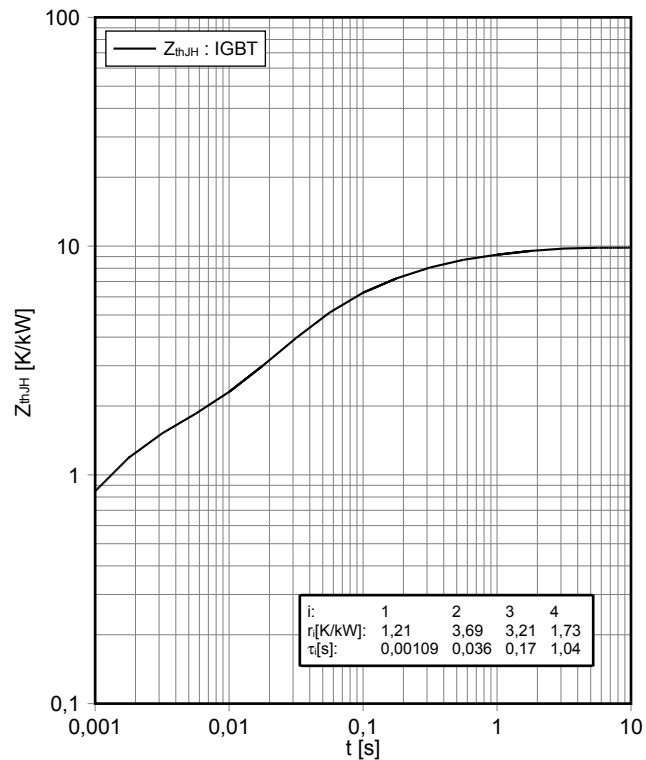
Schaltverluste IGBT, Wechselrichter (typisch) switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}, I_C = 3600 \text{ A}, V_{CE} = 900 \text{ V}$



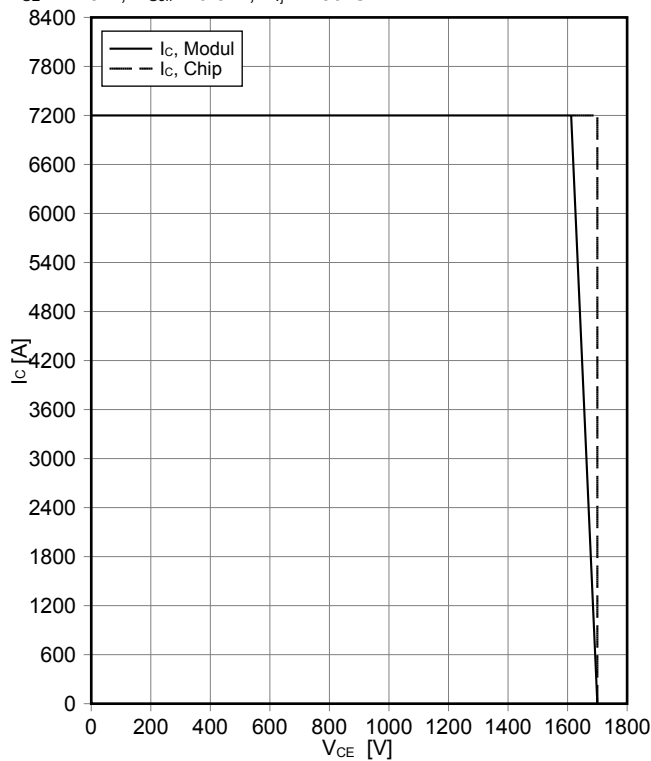
Transienter Wärmewiderstand IGBT, Wechselrichter transient thermal impedance IGBT, Inverter

$Z_{thJH} = f(t)$



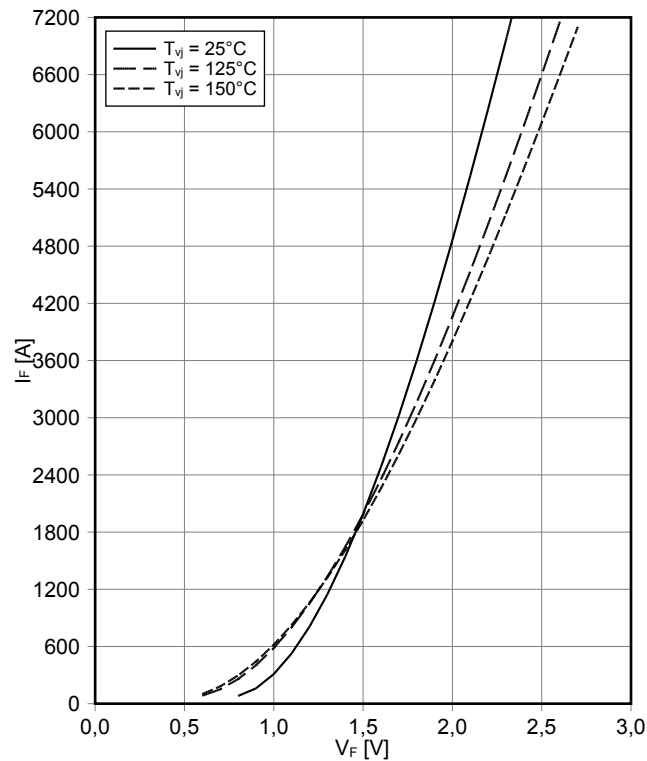
Sicherer Rückwärts-Arbeitsbereich IGBT, Wechselrichter (RBSOA) reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 \text{ V}, R_{Goff} = 0.5 \Omega, T_{vj} = 150^\circ\text{C}$



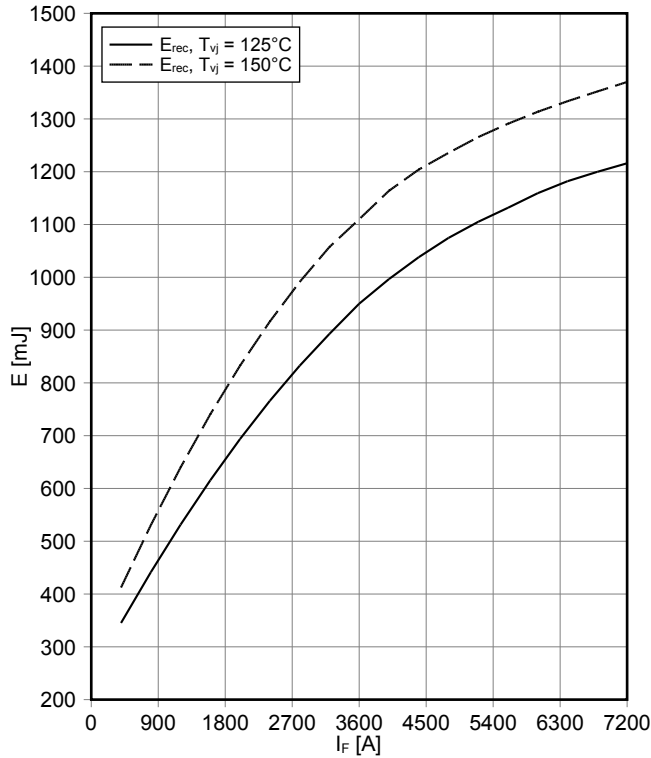
Durchlasskennlinie der Diode, Wechselrichter (typisch) forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$



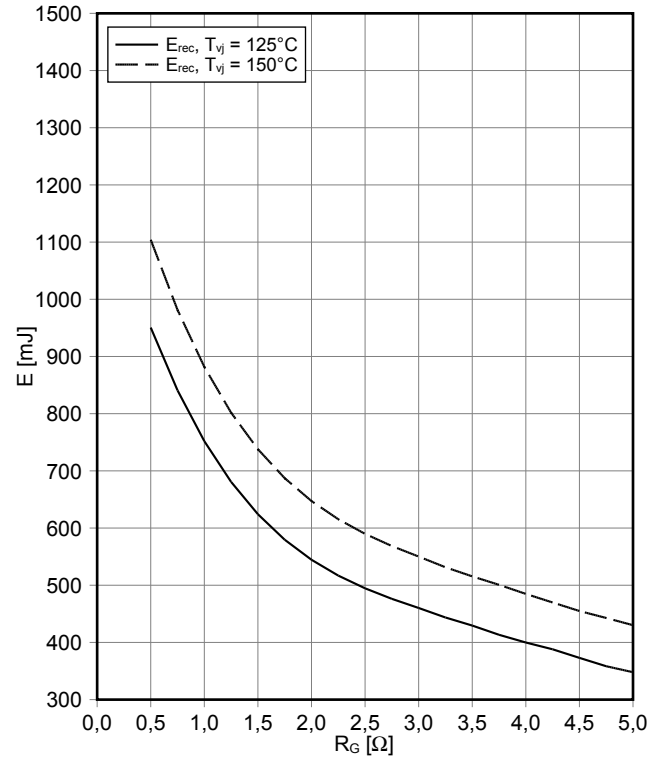
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 0.5 \Omega, V_{CE} = 900 V$



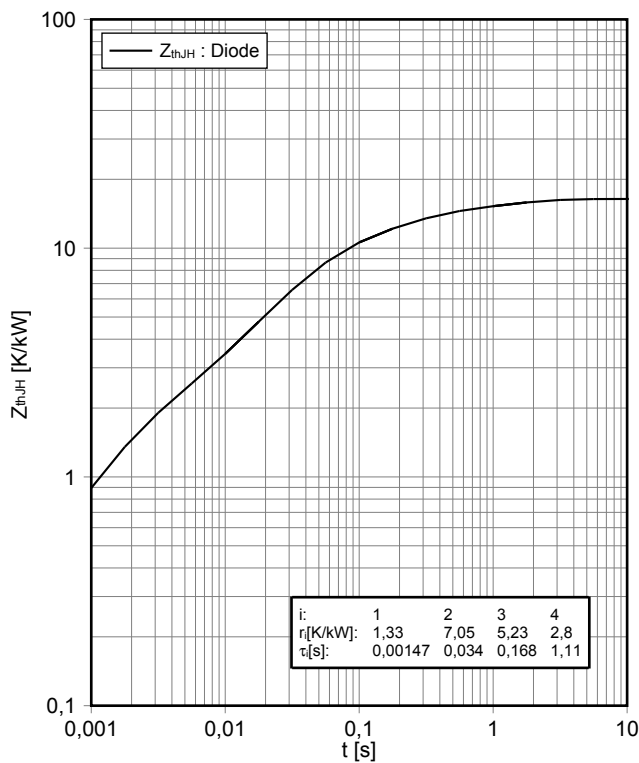
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 3600 A, V_{CE} = 900 V$

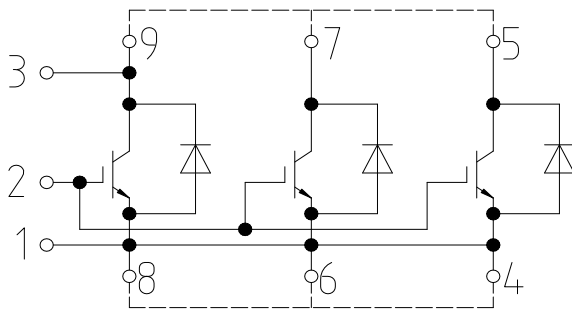


Transienter Wärmewiderstand Diode, Wechselrichter
transient thermal impedance Diode, Inverter

$Z_{thJH} = f(t)$



Schaltplan / Circuit diagram



external connection
(to be done)

Gehäuseabmessungen / Package outlines

